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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# MA2S1010G

## Silicon epitaxial planar type

For switching circuits

### ■ Features

- High breakdown voltage:  $V_R = 250$  V
- Small terminal capacitance  $C_t$
- Suitable for high-density mounting

### ■ Package

- Code  
SSMini2-F4
- Pin Name  
1: Anode  
2: Cathode

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	250	V
Repetitive peak reverse voltage	$V_{RRM}$	250	V
Forward current	$I_F$	100	mA
Peak forward current	$I_{FM}$	225	mA
Non-repetitive peak forward surge current *	$I_{FSM}$	500	mA
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

### ■ Marking Symbol: 1P

Note) \*:  $t = 1$  s

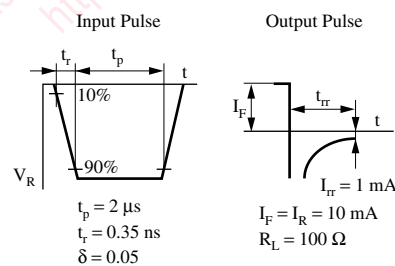
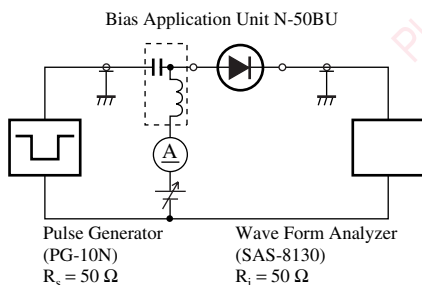
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

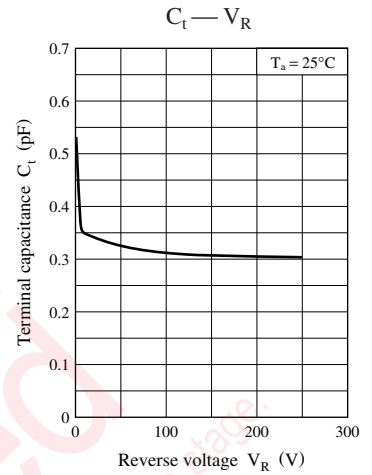
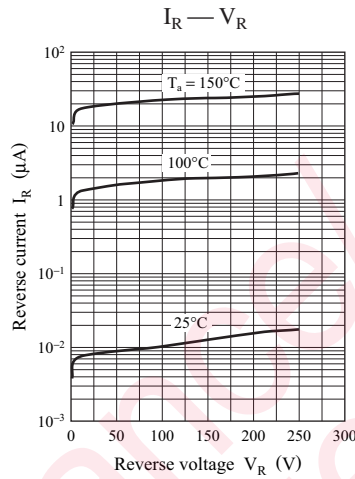
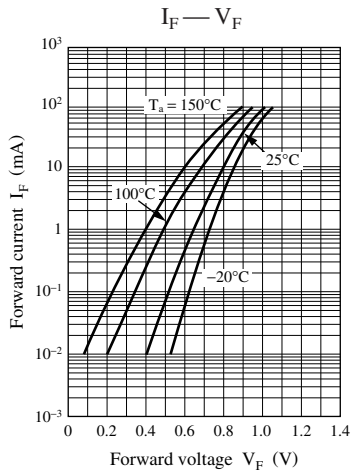
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 70$ mA			1.2	V
Reverse current	$I_R$	$V_R = 250$ V			1.0	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz			3.0	pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 10$ mA $I_{rr} = 1$ mA, $R_L = 100$ $\Omega$			60	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 20 MHz.

3. \*:  $t_{rr}$  measurement circuit

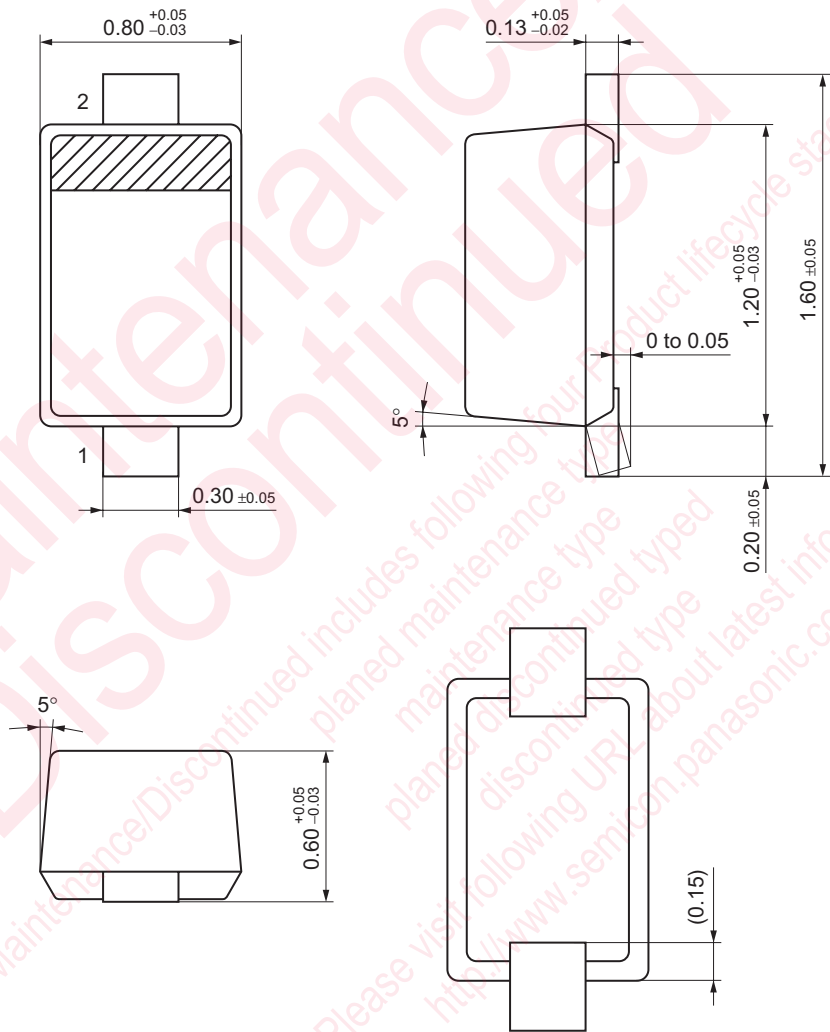




Maintenance/Discontinued includes following four Product lifecycle stages:  
 planned maintenance type  
 maintenance type  
 planned discontinued type  
 discontinued type  
 Please visit following URL about latest information.  
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SSMini2-F4

Unit: mm



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